







(1,27 mm) .050"

SEAF-RA SERIES

HI-DENSITY RIGHT ANGLE OPEN

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAF-RA

Insulator Material: Black LCP Contact Material: Copper Alloy **Current Rating:** 2.1 A per pin (4 adjacent pins powered) Operating Temp Range:
-55°C to +125°C
Plating:
Au or Sn over
50µ" (1,27 µm) Ni
Contact Resistance:

17.1 mΩ max Working Voltage: Mated Cycles: 100

RoHS Compliant: Yes Lead-Free Solderable: Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

 Other platings Contact Samtec. 20, -30,40, --50

NO. OF ROWS	Α	В	С
-04	(13,26) .522	(13,77) .542	(7,91) .311
-06	(15,80) .622	(16,31) .642	(10,45) .411
-08	(18,34) .722	(18,85) .742	(12,99) .511
-10	(20,88) .822	(21,39) .842	(15,53) .611

SEAF

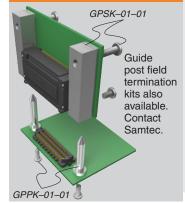
TEST DATA*	SEAF-RA/ SEAM-02	SEAF-RA/ SEAM-RA
Single- Ended	25 Gbps	24 Gbps
Differential Pair	26 Gbps	22 Gbps

*@ 3dB insertion loss. Test board losses de-embedded from performance data.

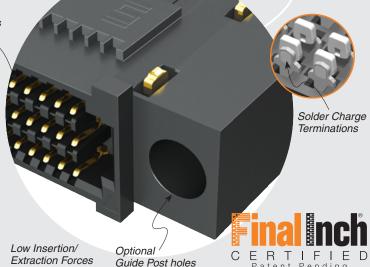
Complete test data available at www.samtec.com?SEAF-RA or contact sig@samtec.com

Mates with: SEAM, SEAMP, SEAC Up to 500 Pins

OTHER SOLUTIONS



PER ROW



PLATING OPTION

= 10µ" (0,25 µm)

Gold on contact area,

Matte Tin on solder tail

-S

= 30μ" (0,76 μm) Gold on contact area,

Matte Tin on solder tail

NO. OF **ROWS**

-04

= Four Rows

-06

= Six Rows

-08*

= Eight Rows

-10* = Ten Rows **SOLDER TYPE**

Tin/Lead Alloy

Solder Charge

-2

= Lead-Free

Solder Charge

OPTION

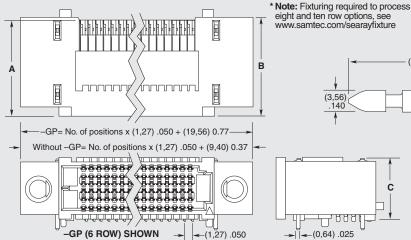
=Tape

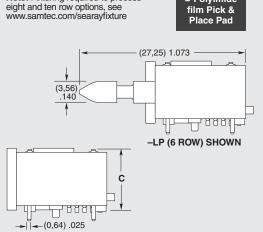
-GP = Guide Post Hole

& Reel -LP

= Latch Post (06 row 30 positions only) (Mates to SEAC Series)

> –K = Polyimide film Pick & Place Pad





Note: Some sizes, styles and options are non-standard, non-returnable.